

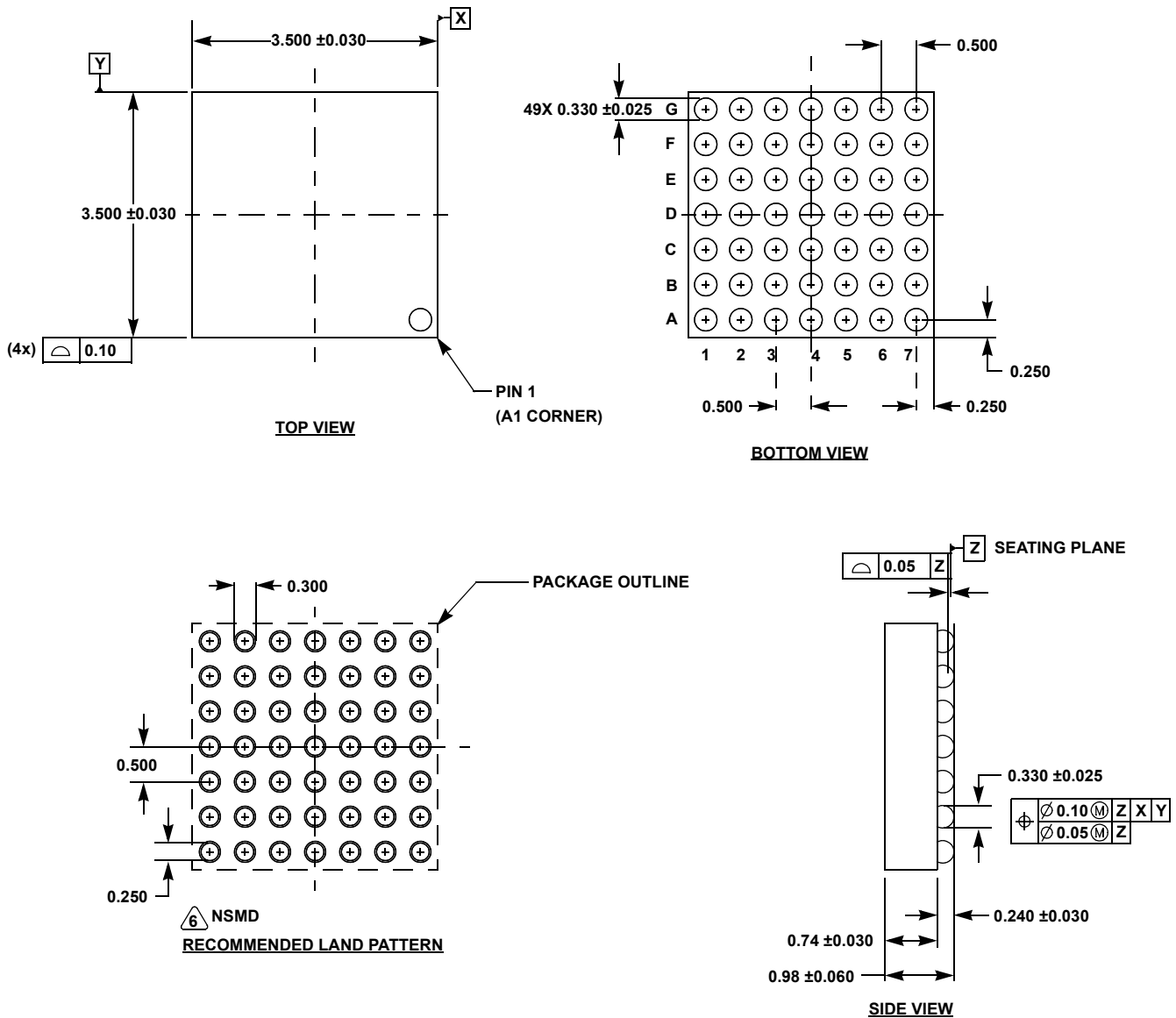
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### W7x7.49C

49 Ball Wafer Level Chip Scale Package (WLCSP 0.5mm Pitch)

Rev 0, 6/16



#### NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerances per ASME Y14.5 - 1994.
3. Primary datum  $Z$  and seating plane are defined by the spherical crowns of the bump.
4. Dimension is measured at the maximum bump diameter parallel to primary datum  $Z$ .
5. Bump position designation per JESD 95-1, SPP-010.
6.  $\overline{\Delta}$  NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).